

Silver - The Cultural
Pride of India

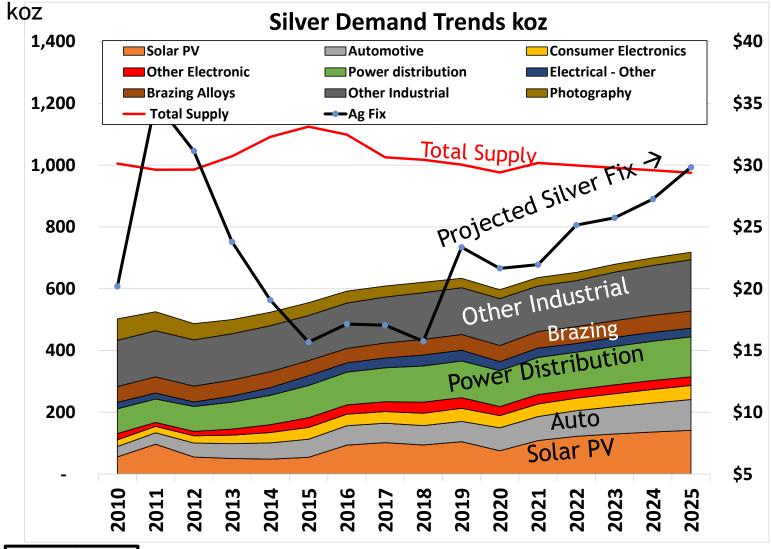
世**SILVERINSTITUTE**



October, 2020

By: Precious Metals Commodity Management LLC

Silver Industrial Demand Trends





Total supply is mined plus recycle silver.

Industrial silver demand is approaching 60% today, greater than 70% by 2025



5 Areas Of Industrial Demand Focus

Semiconductor and Electronics Demand

Understand the silver products and develop the materials supply chain accordingly.

> Silver Conductive Joining Technologies: ECA / Die Attach, Pastes, Solder Materials, Bonding Wire

2. 5G Wireless Deployment - a Silver Force Multiplier

- 2 decades of steady 5G deployment slow rise
- > IoT (Internet of Things) explosion in the number of connected devices

Automotive Electronics - already > \$1.1 trillion dollar market already and growing

- > Today >40% of a vehicles cost is now electronics, >50% by 2030
- Infotainment, Safety Systems, Auto Body, Powertrain, Chassis & Engine Control

4. Auto & Trucking Electrification

- NEV Types: Hybrid gas/electric, PHEV Plug-in Hybrid Electric, BEV Battery Electric, FCEV Fuel Cell Electric Vehicles.
- More electronics and logic devices come with each wave of electrification

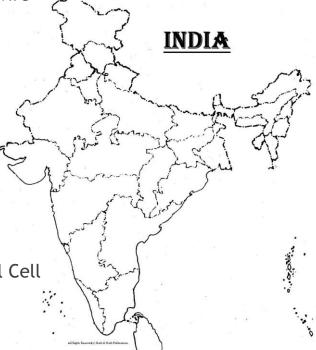
5. Solar PV - Undeniable market growth continues

- > 2019 saw 9% of silver supply consumed in Solar PV, 2020 is a down year
- 2021-25 will be growth years









Legislative Suggestions



- Develop your respective supply chains in these products
- Flakes and powders is a key component, but also <u>nano-materials</u> ← supreme refining is the backbone
- Recycle ... recycle ... recycle Don't just throw in a landfill
- > Don't become the worlds e-waste bucket. Be selective in any imports of e-waste. Mobile phones, data center waste, and IC/Logic devices and PCB's have the highest precious metals content.

2. Li-Batteries - vehicle electrification and energy storage

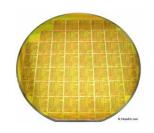
- Advocate for responsible mining in Nickel, Cobalt, and Lithium
- Nickel Mine Tailings directly dumping into our oceans. Indonesia and Papua New Guinea have some of the worst offending miners.
- Regarding Solar PV Storage deployments Be careful on repurposing Li-batteries. Don't become the LiB dumping grounds.
- LiB Recycle absolutely develop this recycle industry. Umicore would be a good corporate partner.

3. Solar PV - Undeniable market growth continues

- Develop your respective supply chain of materials to support this segment.
- Again, develop a recycle capability.
- Consider an upfront Solar PV panel disposal fee. Solar panel recycle costs in USA \$12-14 per 60-cell panel, yet only \$3 of Aluminum, Copper and Silver are recovered.
- Beware of CdTe (Cadmium/Tellurium) and CIGS panels (10% of the PV market) Very toxic materials



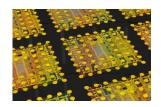


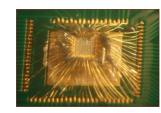


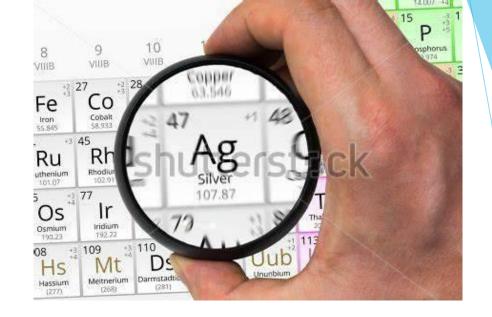






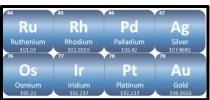






Semiconductor Silver Demand

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Electronic Markets - Classification

Is Everything

Market TAM 2019

(Total Available Market - Revenue)



MEMs Market TAM \$17B Semiconductor

Market

TAM \$412B

Automotive Electronics Market TAM \$1.17

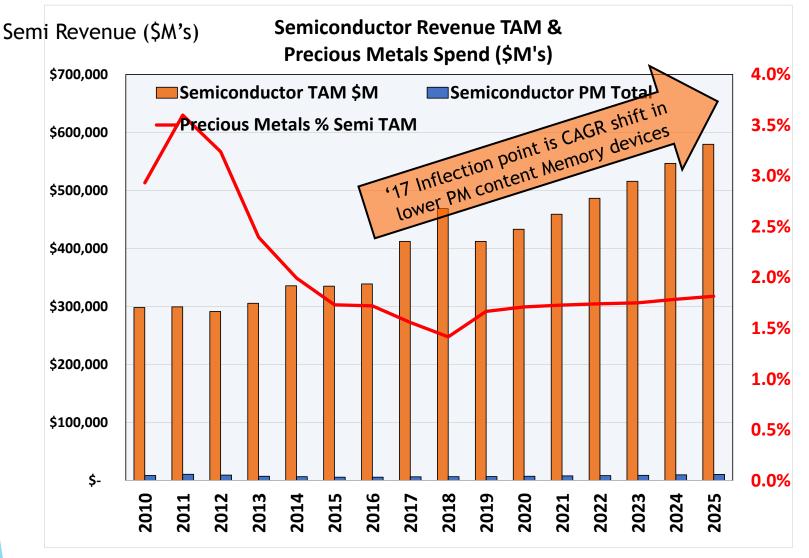
LED / OLED Market TAM \$17B

Flexible Electronics Market TAM \$12B Printed
Electronics
Market
TAM \$50B

Consumer Electronics Market TAM \$1.9T



Semiconductor Silver Demand



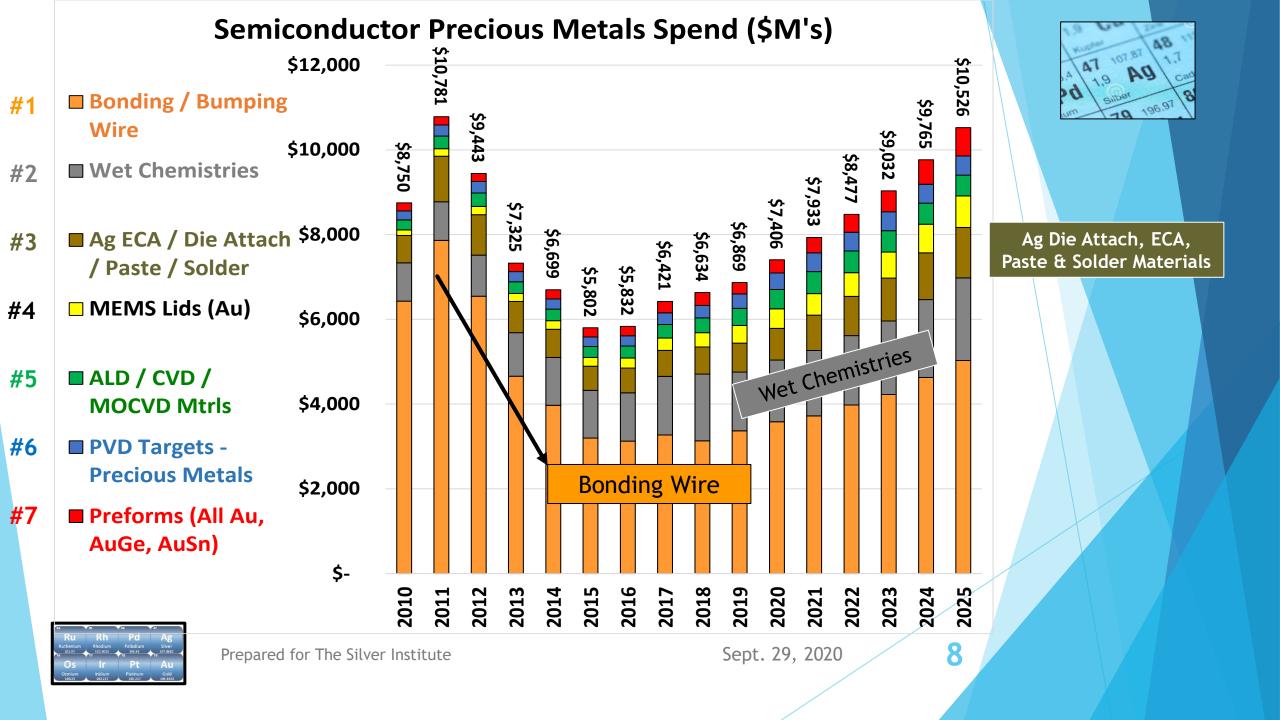


Little precious metals in NAND/DRAM memory, but close to 2% of revenue in Integrated Circuits precious metals materials spend.

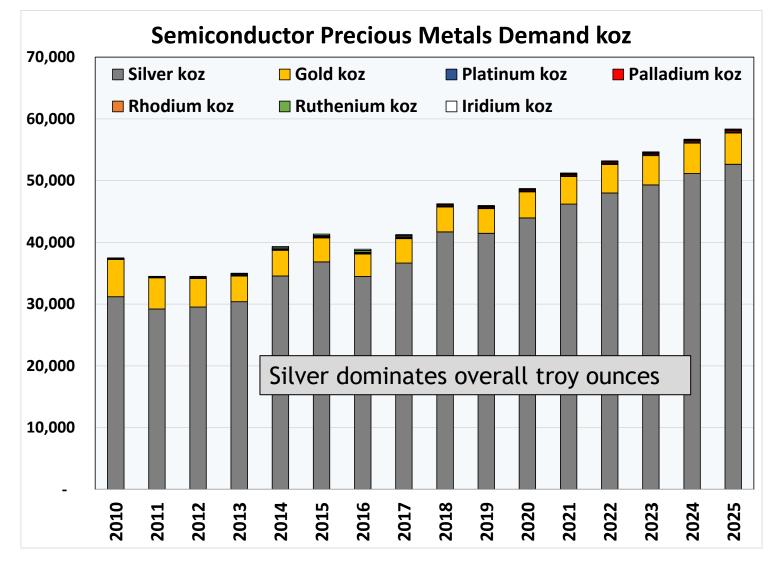
Metals content creeps up with each tighter pitch/node

2018: Memory shortage and pricing 3x inflated Semi TAM.





Semiconductor Precious Metals Demand







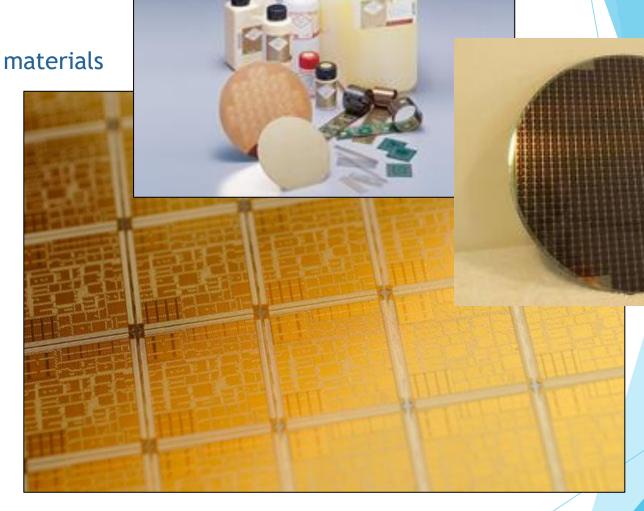
Wet Chemistries

#2 PM Spend Category

Gold is > 90% of the plated materials

- Gold electroplating
- Gold alloy electroplating
- Gold strike plating
- Electro-less gold plating
- Silver plating
- Platinum group
- Rhodium plating
- Ruthenium plating

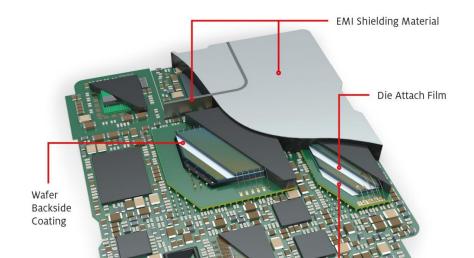






Ag Joining Technologies: Brazing Materials, ECA, Die Attach Materials

#3 PM Spend Category



Encapsulant



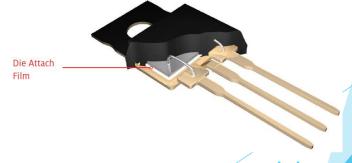
PRODUCT	DESCRIPTION	KEY ATTRIBUTES	DIE SIZE (mm)	SUBSTRATE FINISH	MOISTURE SENSITIVITY LEVEL, MSL	VOLUME RESISTIVITY (Ohm·cm)	THERMAL CONDUCTIVITY (W/m·K)	RECOMMENDED CURE
LOCTITE ABLESTIK 2000	Ag-filled die attach adhesive	Low bleed Low stress Ultra-low moisture absorption Fast oven cure with no voids	≤ 12 x 12	Solder mask or Au	L2 260°C capable	5.0 x 10 ⁻⁴	1.2	30 min. ramp and 15 min. hold at 175°C
LOCTITE ABLESTIK 2100A	Ag-filled die attach adhesive	Low bleed Low stress Oven cure	≤ 12 x 12	Solder mask or Au	L2 260°C capable	5.0 x 10 ⁻²	1.2	30 min. ramp and 15 min. hold at 175°C
LOCTITE ABLESTIK 2300	Ag-filled die attach adhesive	Low bleed Low stress Excellent dispensability Low voiding Oven cure	≤8x8	Solder mask or Au	L2 260°C capable	5.0 x 10 ⁻²	0.6	30 min. ramp and 15 min. hold at 175°C
LOCTITE ABLESTIK 2700HT	Ag-filled die attach adhesive	Excellent bleed performance Long work life Strong hot/ wet adhesion to Au Ideal for small needle dispensing Oven cure	≤ 3 x 3	Solder mask, Ag or Au	L3 260°C capable	3.0 x 10 ⁻⁵	11.0	30 min. ramp and 30 min. hold at 175°C in nitrogen
LOCTITE ABLESTIK ABP 2030SCR	Ag-filled die attach adhesive	Low stress Compatible with dam & fill encapsulants Excellent dispensing performance for high throughput application Snap cure	≤ 10 x 10	Solder mask, Ag, Au or plastics	L3 260°C capable	2.0 x 10 ⁻⁴	2.0	120 sec. at 120°C
LOCTITE ABLESTIK ABP 2032S	Ag-filled, epoxy die attach adhesive	Good adhesion to a variety of substrates Good dispensing characteristics Low temperature oven cure	≤ 10 x 10	Solder mask, Ag, Au, steel or plastics	L3 260°C capable	2.0 x 10 ⁻⁴	1.0	60 min. at 80°C



Solder Paste

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Die Attach Paste



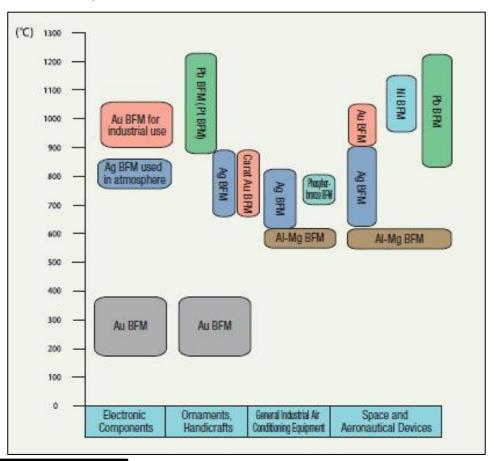
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Die Attach

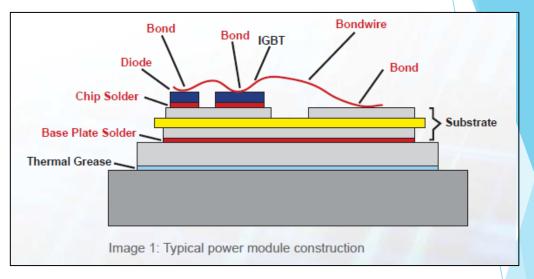
Ag Solder / Brazing Materials

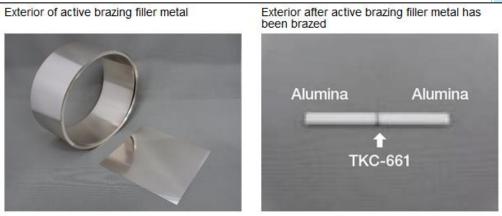
#3 PM Spend Category

Melting Points of various BFM - Brazing Filler Materials



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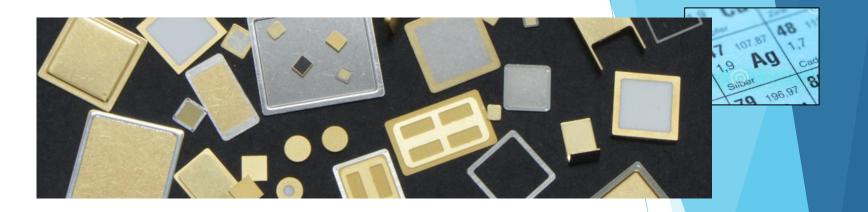


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MEMS Lid's

#4 Semi Precious Metals Send Category





Microelectronic Packaging Comparison Chart

Packaging Products	Applications	Illustrations	Lid Material	Preform
Combo-Lids TM (Flat)	High reliability hermetic packaging		Kovar or Alloy 42	Gold-Tin or other allows
Combo-Lida TM (Drawn)	High reliability hermetic packaging where die height is higher than package cavity deoth	400	Kovar or Alloy 42	Gold-Tin or other alloys
Non-magnetic Metal Combo-Lids TM	Medical Imaging and signal noise control		Mo, CuW, Bronse, Cu	Gold-Tin or other allows
Non-magnetic Metal Combo-Lids TH	High Purity non-magnetic combo lids, does not contain Nickel or plating		Mo, CuW, Bronze, Cu	Gold-Tin or other allors
Non-magnetic BeCu Combo-Lids TM	High Purity non-magnetic combo lids, does not contain Nickel or clating		BeCu	Gold-Tin or other allows
Nozzie Combo-Lidz TM	MEMS, Automotive and High reliability hermetic package sealing		Kovar	Gold-Tin
Ceramic Combo-Lids TM with edge metallization	Non-magnetic applications	5	Al ₂ O ₃	Gold-Tin or other allows
Tack welding services for Ceramic Lids	Non-magnetic applications		AlgOg	Gold-Tin or other allows

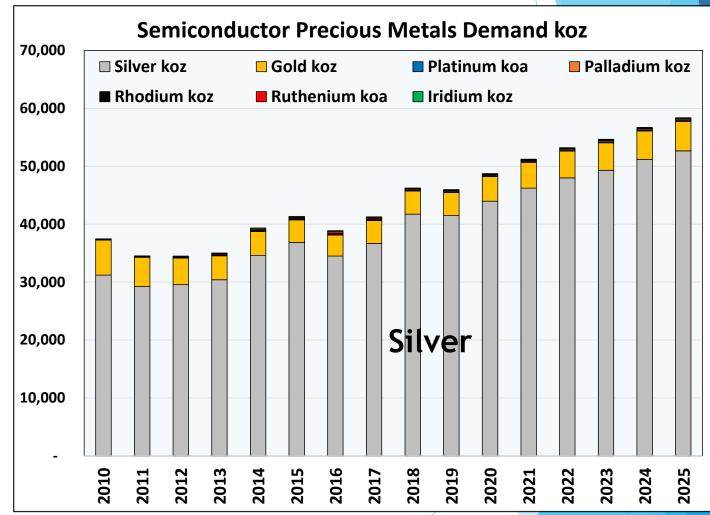
Selectively plated Combo-Lids TM	High reliability hermetic package sealing		Kovar or Al ₂ O ₃	Gold-Tin or other allows
Getter Tack welded Combo-Lids TM	High reliability hermetic package sealing		Kovar	Gold-Tin or other alloys
Paladium Combo-Lida TM	High reliability hermetic package sealing		Kovar with Palladium	Gold-Tin or other allows
Seam Seal-Lida TM	Hermetic oackage sealing without preform	1	Kovar	-
Special Shaped Combo-Lida TH	High reliability hermetic package sealing	00	Kovar	Gold-Tin
Ecc-Lids TH	Ceramic Lid for non-hermetic packages including CuPacks TM	***	Al ₂ O ₃	MEG-150 or MEG-165 Epoxy
Ceramic Air Cavity Packages	Wireless Applications - St, GaAs and GaN RF power translators		Allor 42 plated with Ni, NiCo, Au	Alumina rinz frames
Etch Lids for AR Costed Class	Double preform attached lid for Visi-Lid TM application		Kovar	Gold-Tin or other allows



Silver Use in Semiconductor Is Growing Summary: PM Demand in Semi



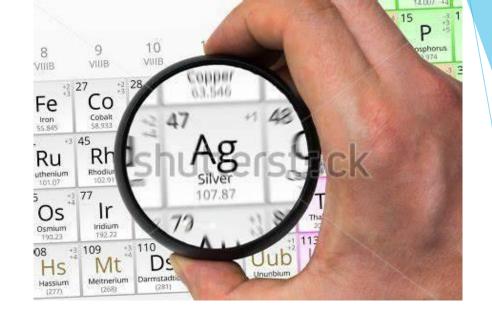
- Flip Chip and WLP (Wafer Level Processing) is creating additional demands for conductive adhesives
- Surface mount of packages, and device in device mounting and electrical connection are increasing the use of conductive adhesives in all areas.
- Modest demand growth from Silver bonding wire. Linear meters are growing, while thrifting is achieved with less pure gold and smaller diameter wire,





Automotive

- Auto Semiconductor
- Auto Electronics
- Spark Plugs
- 10% of these categories
 - Contacts & Materials
 - Electrical Connectors



Automotive Silver Demand



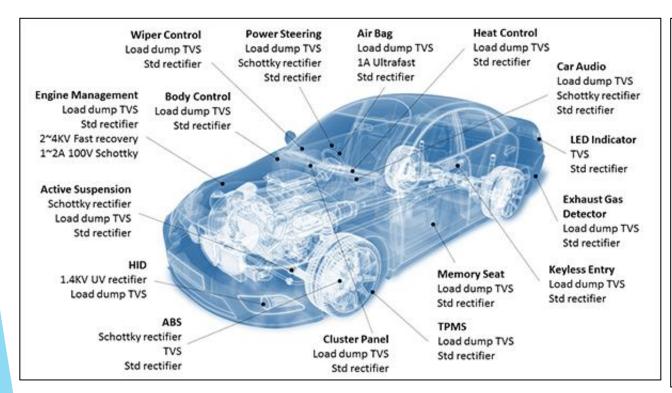


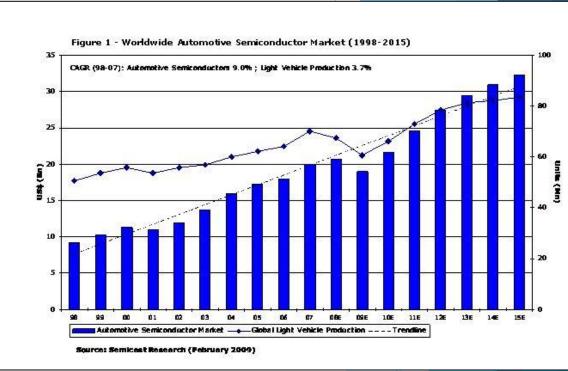
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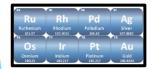
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Automotive Electronics Market Growth







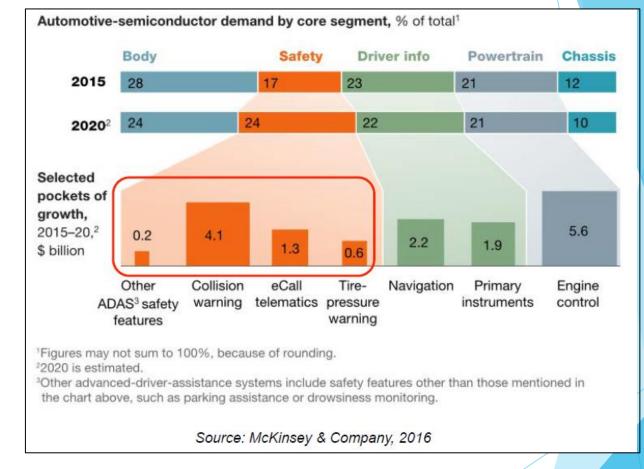


Automotive Electronics Main Spend Areas



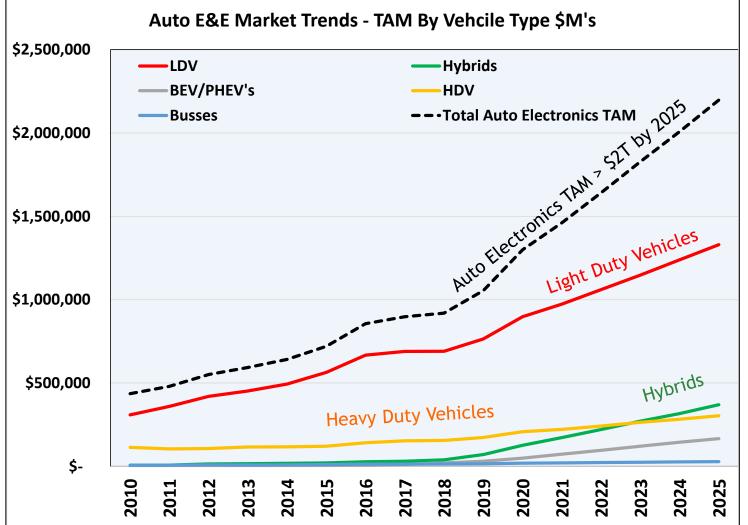
5 Main Categories:

- 1) Body
- 2) Safety Systems
- 3) Driver Information /Infotainment
- 4) Powertrain
- 5) Chassis & Engine Control
- ☐ Future: BEV/PHEV/FCEV
 Related Electronics





Auto Silver Demand By Vehicle Category





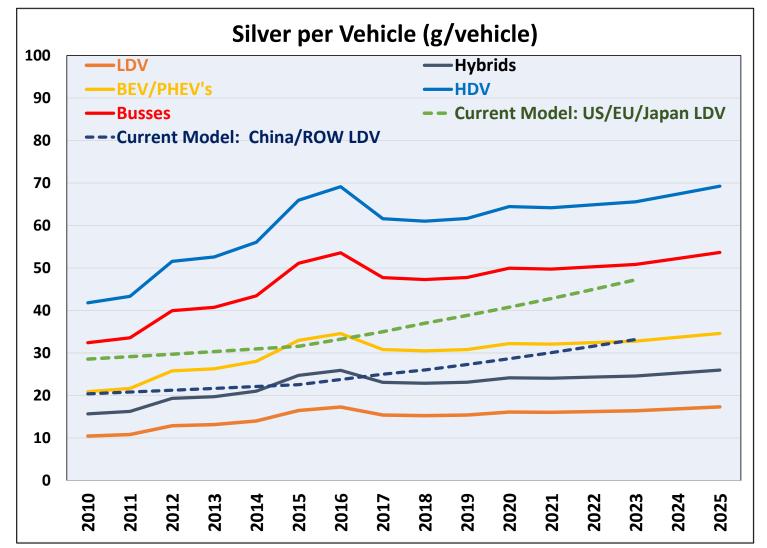
BEV;s/PHEV's

Busses

18



Automotive Silver Demand



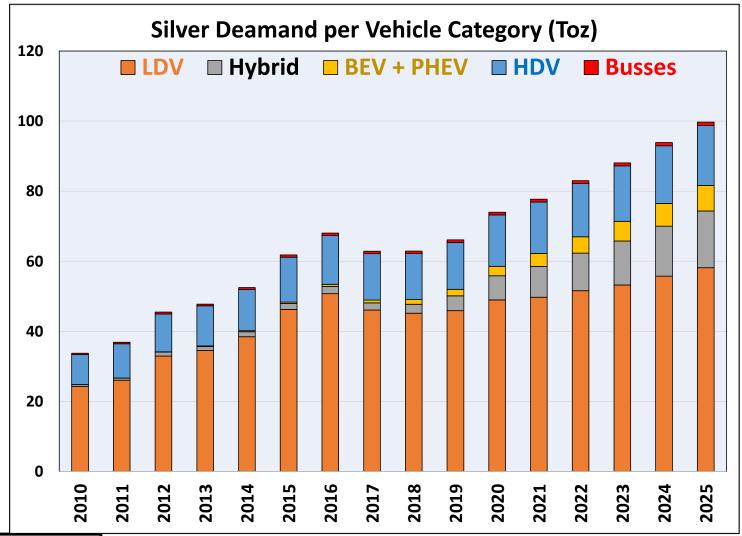


The shift in vehicle mix more than the increase in electronics loading over time will increase the silver auto demand the most.

Hybrids and BEV/PHEV's use 1.5x to 2x the loadings.



Total Automotive Silver Demand





Automotive

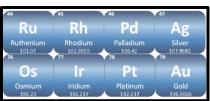
- Auto Semiconductor
- Auto Electronics
- Spark Plugs
- 10% of these categories
 - Contacts & Materials
 - Electrical Connectors





Solar PV Silver Demand

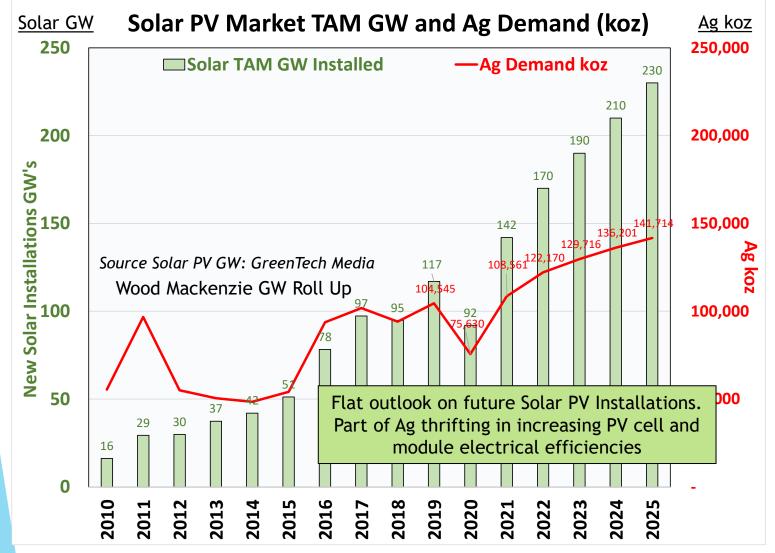




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Solar PV Market & Ag Demand (koz)



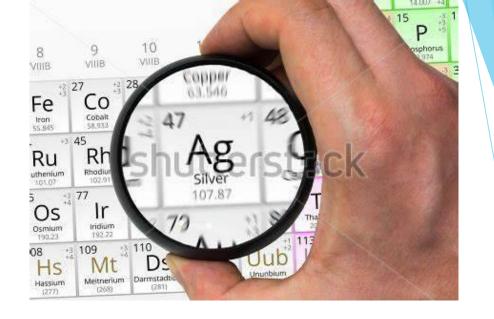
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Getting Wood Mackenzie GW Forecast in November. Using PV Magazine Solar Powe EU reference data until then.

Design thrifting historical used to forecast thrifting going forward.





Thank You

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